ON Semiconductor				10/15/2019
Base Part		FCH041N60F		
Orderable Part		FCH041N60F	Total weight (mg)	5456.725
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	32	Silicon (Si)	7440-21-3	100
Die Attach Solder	35.025	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	3612.9	Zinc (Zn)	7440-66-6	0.04843754
		Nickel (Ni)	7440-02-0	3.26607434
		Iron (Fe)	7439-89-6	0.05812505
		Copper (Cu)	7440-50-8	96.59830053
		Phosphorus (P)	7723-14-0	0.02906253
Mold Compound-Black	1739.8	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8	1.2012875
		Ortho Cresol Novolac Resin	29690-82-2	16.32371537
		Antimony Trioxide (Sb2O3)	1309-64-4	2.0059777
		Carbon Black (C)	1333-86-4	1.00011496
		Fused Silica (SiO2)	60676-86-0	79.46890447
Plating	31	Tin (Sn)	7440-31-5	100
Wire Bond - Al	6	Aluminum (Al)	7429-90-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF